

# BB152

## VHF variable capacitance diode

Rev. 4 — 5 September 2011

Product data sheet

## 1. Product profile

### 1.1 General description

The BB152 is a variable capacitance diode, fabricated in planar technology and encapsulated in the SOD323 (SC-76) very small SMD plastic package.

The excellent matching performance is achieved by gliding matching and a Direct Matching Assembly (DMA) procedure.

### 1.2 Features and benefits



- High linearity
- Excellent matching to 2 % DMA
- Very small SMD plastic package
- $C_{d(28V)}$ : 2.7 pF;  $C_{d(1V)}$  to  $C_{d(28V)}$  ratio: 22
- Low series resistance.

### 1.3 Applications

- Electronic tuning in VHF television tuners, band A up to 160 MHz
- Voltage Controlled Oscillators (VCO).

## 2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline <sup>[1]</sup>	Symbol
1	cathode		 <i>sym008</i>
2	anode		

[1] The marking bar indicates the cathode.

## 3. Ordering information

Table 2. Ordering information

Type number	Package		Version
	Name	Description	
BB152	SC-76	plastic surface mounted package; 2 leads	SOD323



## 4. Marking

**Table 3. Marking**

Type number	Marking code
BB152	PB

## 5. Limiting values

**Table 4. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

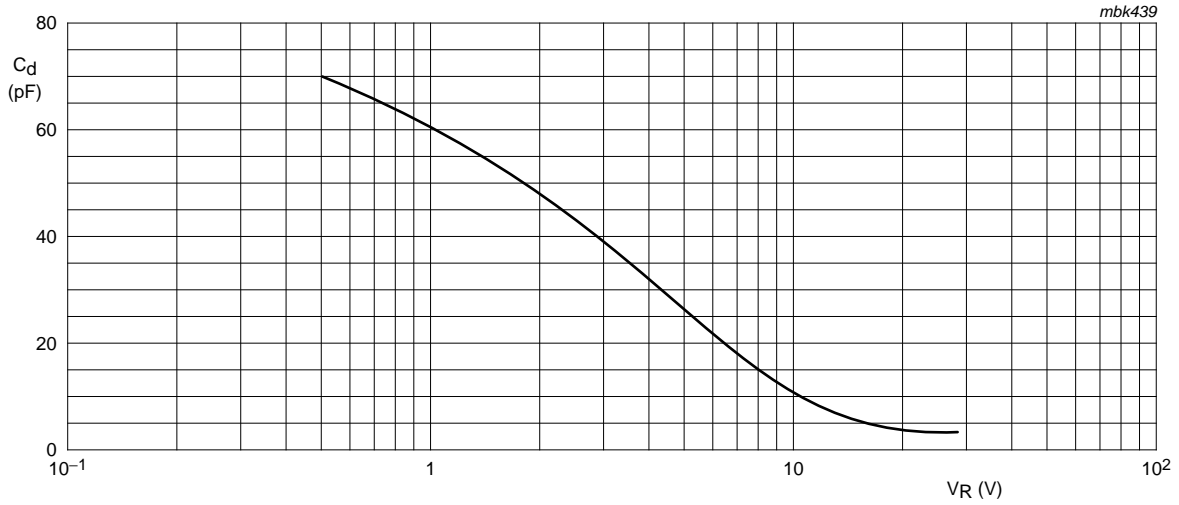
Symbol	Parameter	Conditions	Min	Max	Unit
$V_R$	reverse voltage		-	32	V
$V_{RM}$	peak reverse voltage	in series with a 10 k $\Omega$ resistor	-	35	V
$I_F$	forward current		-	20	mA
$T_{stg}$	storage temperature		-55	+150	$^{\circ}\text{C}$
$T_j$	junction temperature		-55	+125	$^{\circ}\text{C}$

## 6. Characteristics

**Table 5. Characteristics**

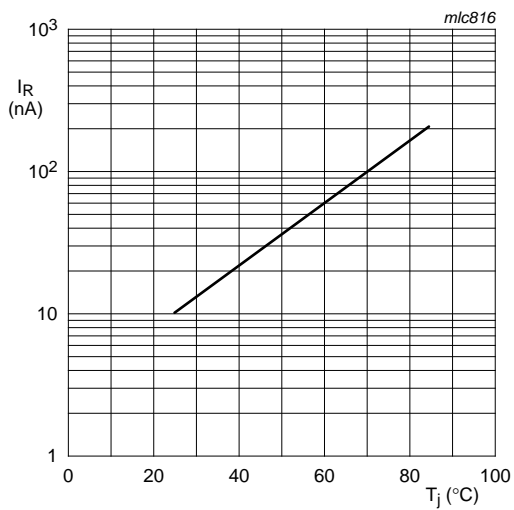
*$T_j = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_R$	reverse current	see <a href="#">Figure 2</a>				
		$V_R = 30\text{ V}$	-	-	10	nA
		$V_R = 30\text{ V}; T_j = 85\text{ }^{\circ}\text{C}$	-	-	200	nA
$r_s$	diode series resistance	$f = 100\text{ MHz}; C_d = 30\text{ pF}$	-	1	1.2	$\Omega$
$C_d$	diode capacitance	$f = 1\text{ MHz};$ see <a href="#">Figure 1</a> and <a href="#">3</a>				
		$V_R = 1\text{ V}$	52	-	62	pF
		$V_R = 28\text{ V}$	2.48	2.7	2.89	pF
$\frac{C_{d(1V)}}{C_{d(2V)}}$	capacitance ratio	$f = 1\text{ MHz}$	-	1.31	-	
$\frac{C_{d(1V)}}{C_{d(28V)}}$	capacitance ratio	$f = 1\text{ MHz}$	20.6	22	-	
$\frac{C_{d(25V)}}{C_{d(28V)}}$	capacitance ratio	$f = 1\text{ MHz}$	-	1.05	-	
$\frac{\Delta C_d}{C_d}$	capacitance matching	$V_R = 1\text{ V to } 28\text{ V};$ in a sequence of 10 diodes (gliding)	-	-	2	%

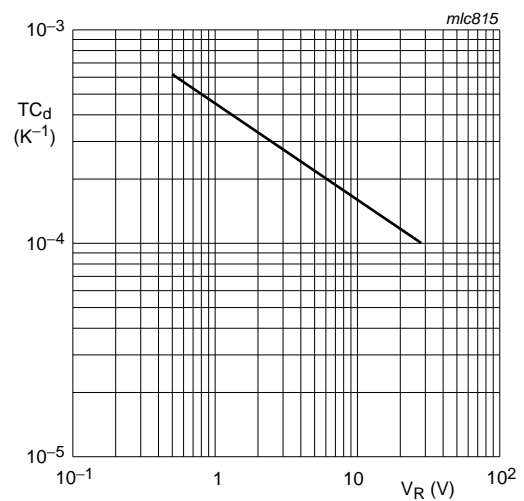


$f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}.$

**Fig 1. Diode capacitance as a function of reverse voltage; typical values.**



**Fig 2. Reverse current as a function of junction temperature; maximum values.**



$T_j = 0 \text{ }^\circ\text{C} \text{ to } 85 \text{ }^\circ\text{C}.$

**Fig 3. Temperature coefficient of diode capacitance as a function of reverse voltage; typical values.**

## 7. Package outline

Plastic surface-mounted package; 2 leads

SOD323

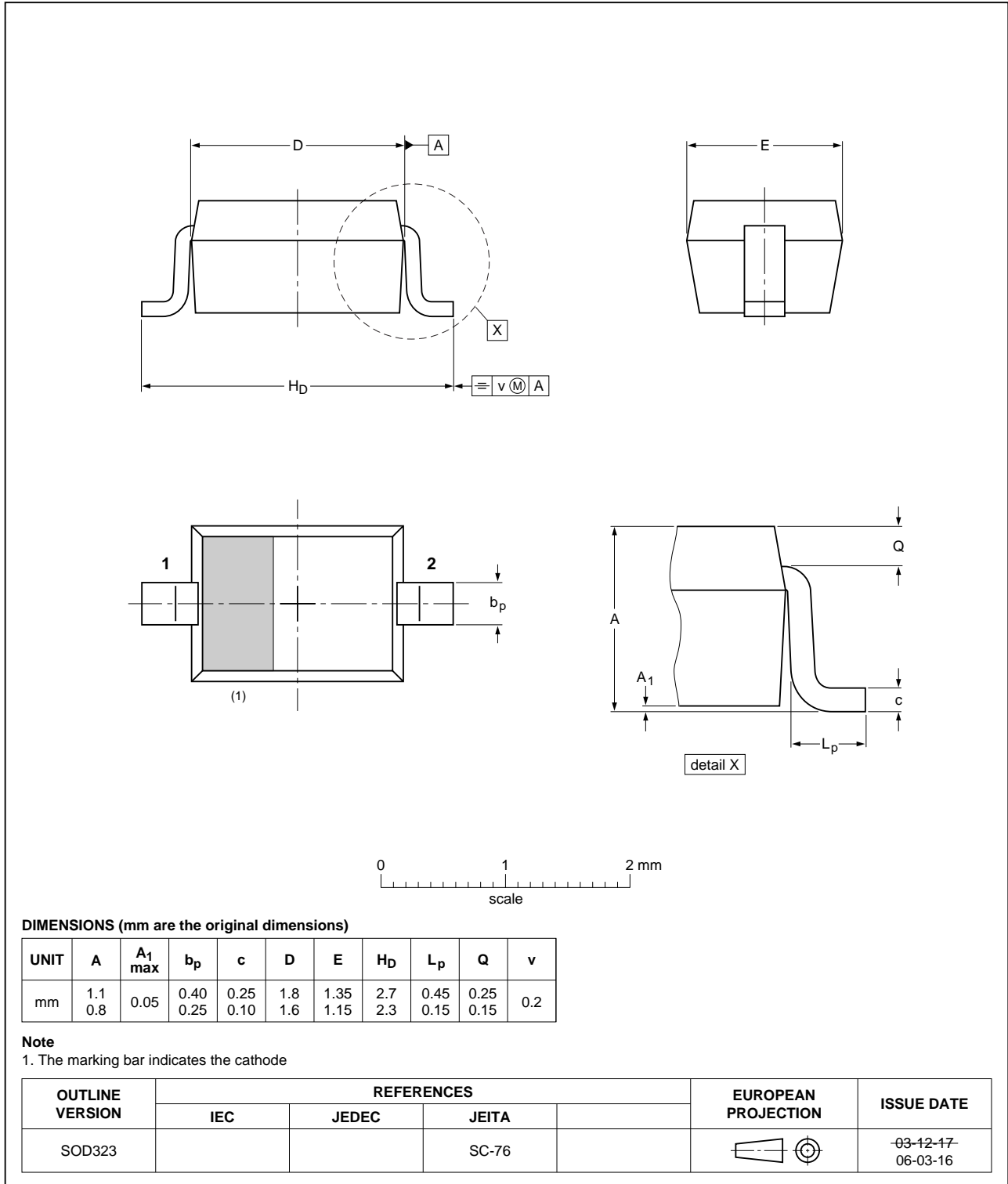


Fig 4. Package outline SOD323 (SC-76).

## 8. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BB152 v.4	20110905	Product data sheet	-	BB152 v.3
Modifications:		<ul style="list-style-type: none"><li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>• Legal texts have been adapted to the new company name where appropriate.</li><li>• Package outline drawings have been updated to the latest version.</li></ul>		
BB152 v.3 (9397 750 13828)	20041005	Product data sheet	-	BB152 v.2
BB152 v.2 (9397 750 12645)	20040225	Product specification	-	BB152 v.1
BB152 v.1 (9397 750 04275)	19980909	Product specification	-	-

## 9. Legal information

### 9.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Date of release: 5 September 2011

Document identifier: BB152